

Bright Tin CULMO 20

Brigt Tin CULMO 20 is based upon sulphuric acid, free from formalin and deposits bright tin layers. These layers are resistant to fingerprints and show good solderability even after an accelerated aging test e.g. 16 h at 155 °C.

Bright Tin CULMO 20 is weakly foaming and especially suitable for barrel plating. It may also be used in continuous plating lines, if a good electrolyte exchange and large anode surface can be assured. Electrolyte exchange and metal content determine the applicable cathodic current density.

Bright Tin CULMO 20 is extraordinary stable and easy to handle.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance only. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.